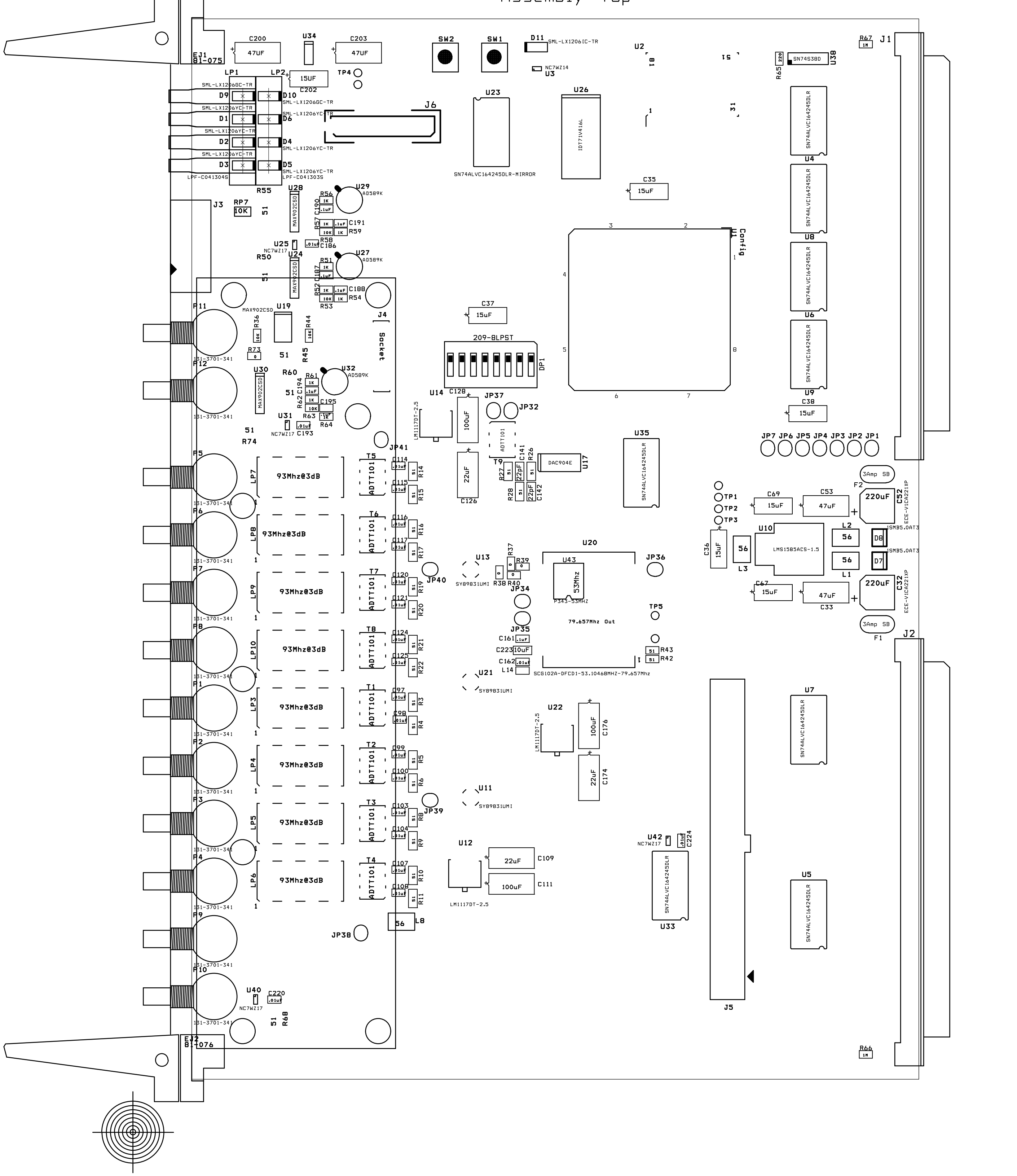
BPM Timing Fanout Card
Rev 1.0, June 3 2004

Assembly Top



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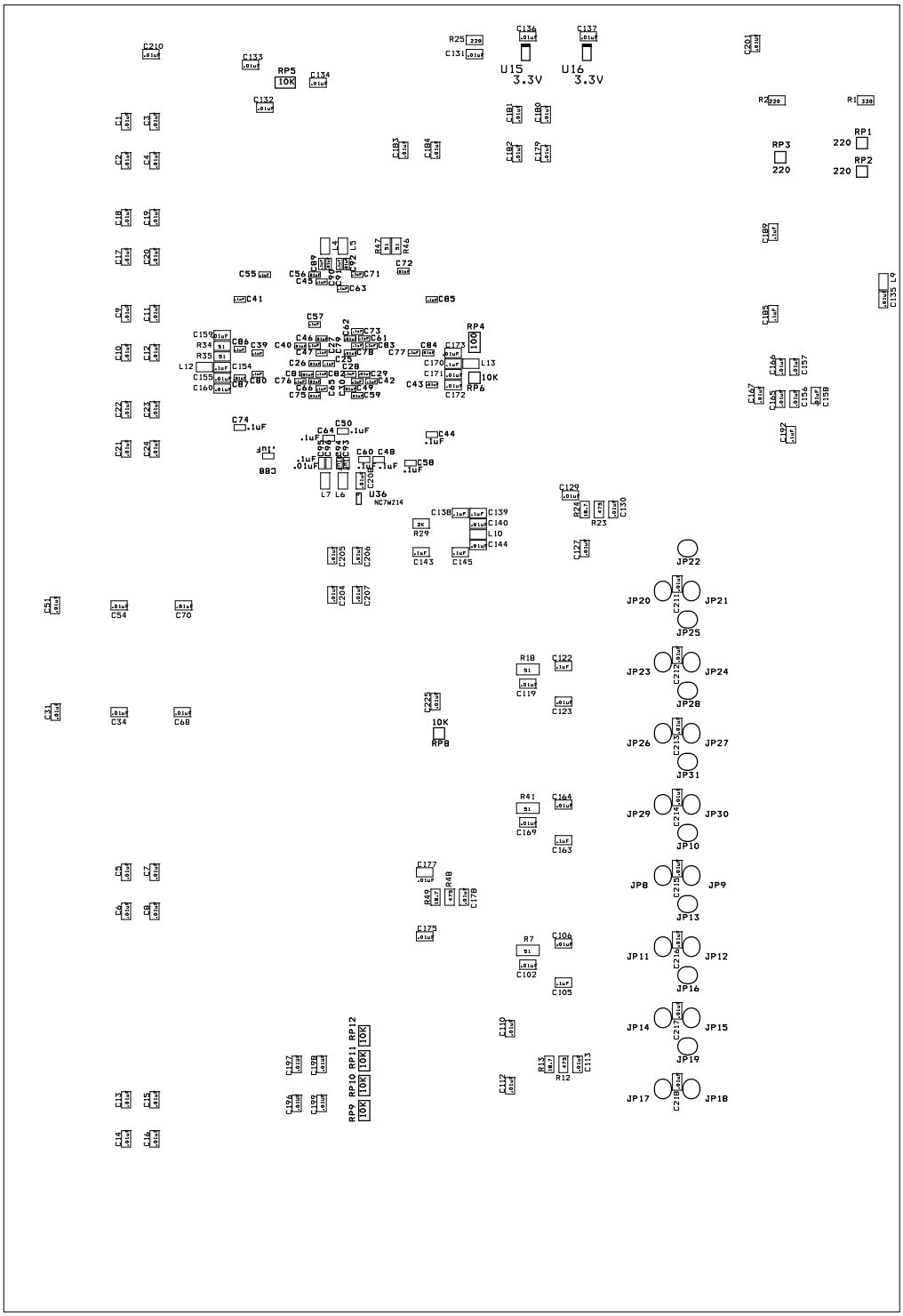
Assembly Bottom



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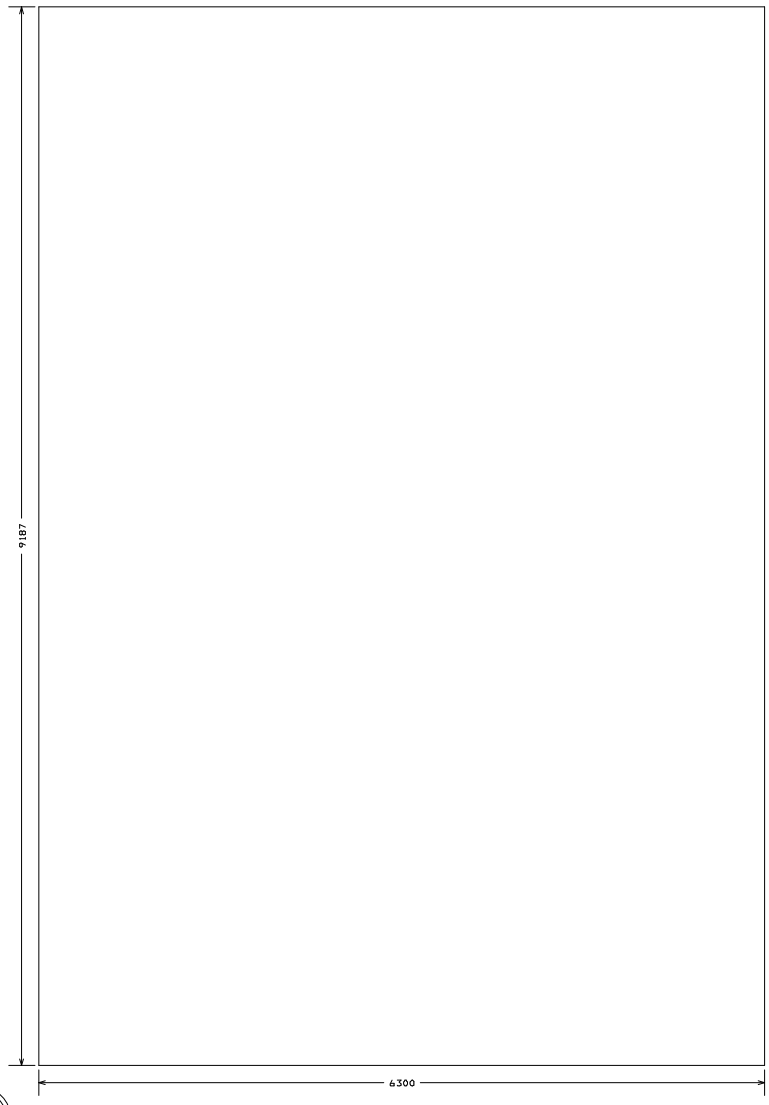
Fabrication Drawing



Layer Stackup:

1) Component Side
2) Ground Plane: Analog
3) Inner Layer1
4) Inner Layer2
5) Power - VCC/1.5V
6) Power VDD
7) Inner Layer3
8) Inner Layer4
9) Ground Plane: Digital
10) Solder Side

SMT Pad Count:

Top: 1930
Bottom: 502

Thru Hole Count: 2002

Job Spec's

Material: FR-4
Material Thickness: 0.063"
Copper Weight: 1/2oz Inner/Outer Layers
Finnish/Plating: Tin-Lead
SolderMask Type: LPI
SilkScreen Layers: Top & Bottom
Min. Trace Width: 5mil
Min. Trace Spacing: 5mil
Smallest Hole Size: 10mil
Largest Hole Size: 125mil
Job Turn Around Time: 10 Day Turn
Job Qnt.: 5 Pieces

Controled Impedence:

All Top Layer 9mil traces are to be 50ohms to Layer 2 GND Plane

All Bottom Layer 9mil traces are to be 50ohms to Layer 11 GND Plane